

| REV. | ECN. NO. | APPD. |
|------|---------------|--------------|
| A | BC-14-0065178 | Adward Zheng |
| B | BC-16-0017921 | LIANG GONG |
| BX1 | 1/17'18 | Davy Bu |
| BX2 | 1/19'18 | Davy Bu |

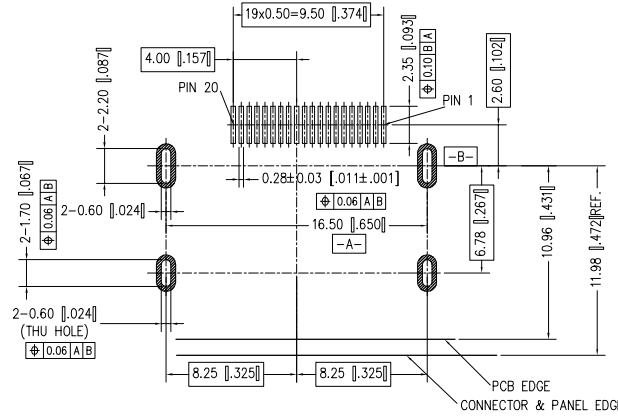
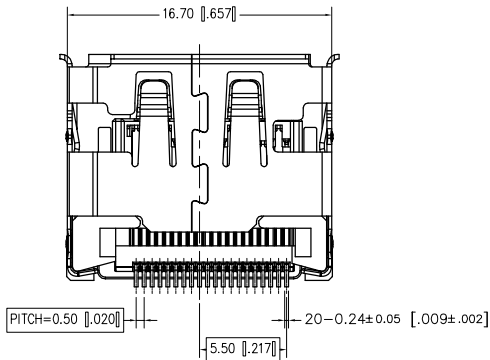
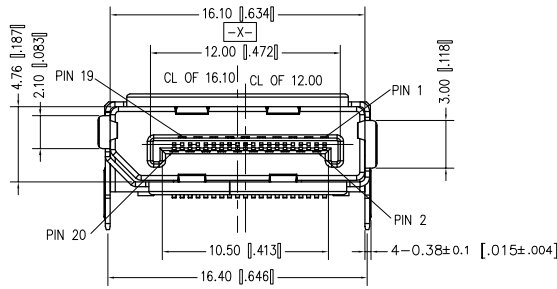
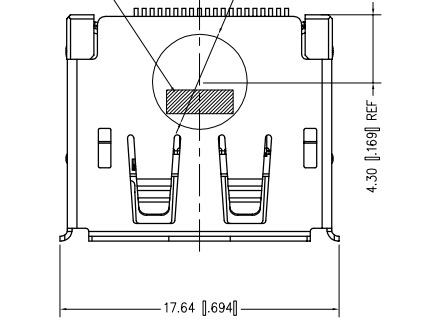
PRODUCT NO.: 3V * * * * *

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| DISPLAY PORT SERIES | HALOGEN-FREE CODE |
| PRODUCT SERIES: D: STANDARD TYPE | PACKAGE CODE: 4: SOFT TRAY 7: TAPE REEL |
| TERMINATION TYPE: 5: R/A SMT | EXTENSION CODE |
| CONNECTOR TYPE: 1: RECEPTACLE 20: 20 POS | CONTACT GOLD PLATING: 1: 1u" GOLD 3: 30u" GOLD 7: 15u" GOLD |

NOTES:

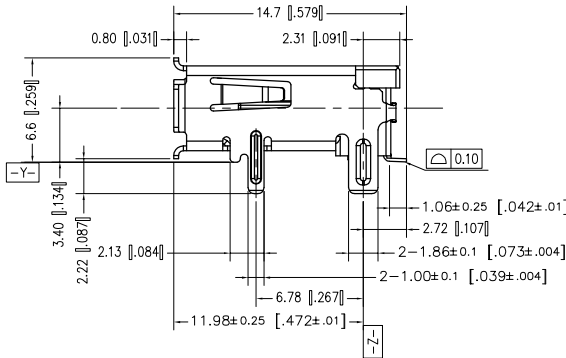
- 1. ELECTRICAL CHARACTERISTICS:
 - 1-1. CONTACT CURRENT RATING: 0.5A MIN.
FINGER CURRENT RATING: 1.0A MIN.
APPLIED VOLTAGE RATING: 40V AC
 - 1-2. CONTACT RESISTANCE:
CONTACT RESISTANCE: 30 MILLIOHMS MAXIMUM.
AFTER TEST: CHANGE FROM INITIAL VALUE 30MILLIOHMS MAX.
 - 1-3. SHELL RESISTANCE:
AFTER TEST: CHANGE FROM INITIAL VALUE 50MILLIOHMS MAX.
 - 1-4. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC RMS.
 - 1-5. INSULATION RESISTANCE:
UNMATED PLUG: 100 MEGAOHMS MIN. AT 500V DC.
MATED PLUG: 10 MEGAOHMS MIN. AT 150V DC.
- 2. MECHANICAL CHARACTERISTICS:
 - 2-1. CONNECTOR MATING FORCE: 4.5Kgf MAX.
 - 2-2. CONNECTOR UNMATING FORCE: 1.0~4.0 Kgf.
 - 2-3. DURABILITY: 10000 CYCLES.
 - 2-4. OPERATING TEMPERATURE RANGE: -40~85°C;
HUMIDITY: 85% RH MAX.
- 3. RECOMMENDED PROCESS:
 - 3-1. IR REFLOW, PEAK TEMPERATURE 250°C, 10SEC MAX.
 - 3-2. COPLANARITY OF SMT TERMINAL IS 0.10mm MAX.
- 4. RoHS AND HALOGEN-FREE COMPLIANT.

D/C Area Pickup Area#6.00 [Ø.236] REF



RECOMMENDED P.C.B. LAYOUT (COMPONENT SIDE VIEW)

PCB THICKNESS: 1.60±0.05mm
DEFAULT TOLERANCE: ±0.05



| PIN NUMBER | SOURCE-SIDE PIN ASSIGNMENT | SINK-SIDE PIN ASSIGNMENT |
|------------|----------------------------|--------------------------|
| 1 | ML_Lane 0(p) | ML_Lane 3(n) |
| 2 | GND | GND |
| 3 | ML_Lane 0(n) | ML_Lane 3(p) |
| 4 | ML_Lane 1(p) | ML_Lane 2(n) |
| 5 | GND | GND |
| 6 | ML_Lane 1(n) | ML_Lane 2(p) |
| 7 | ML_Lane 2(p) | ML_Lane 1(n) |
| 8 | GND | GND |
| 9 | ML_Lane 2(n) | ML_Lane 1(p) |
| 10 | ML_Lane 3(p) | ML_Lane 0(n) |
| 11 | GND | GND |
| 12 | ML_Lane 3(n) | ML_Lane 0(p) |
| 13 | CONFIG1 | CONFIG1 |
| 14 | CONFIG2 | CONFIG2 |
| 15 | AUX CH (p) | AUX CH (p) |
| 16 | GND | GND |
| 17 | AUX CH (n) | AUX CH (n) |
| 18 | HOT PLUG DETECT | HOT PLUG DETECT |
| 19 | RETURN | RETURN |
| 20 | DP PWR | DP PWR |

| ITEM | DESCRIPTION | Q'TY | MATERIAL | REMARK |
|------|-------------|------|--|--|
| ③ | CONTACT | 20 | COPPER ALLOY | NIKEL UNDERPLATING OVERALL, 30u" MIN. AU PLATING AT CONTACT AREA, TIN ALLOY(LEAD FREE) PLATING AT SOLDER AREA. |
| ② | HOUSING | 1 | HIGH TEMPERATURE THERMOPLASTIC UL94V-0 | COLOR: BLACK |
| ① | SHELL | 1 | STAINLESS STEEL | NIKEL UNDERPLATING OVERALL, TIN ALLOY(LEAD FREE) PLATING AT SOLDER AREA. |

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|-------|------------------|----------|--------------------|------------------------|--|-----------------|----------|---------------|
| X.± | X.± | UNITS | NAME(INTENDED USE) | | FOXCONN INTERCONNECT TECHNOLOGY LIMITED. | | | |
| | | mm[INCH] | CUSTOMER | | | | | |
| | .X± 0.30[0.015] | .X'± | MAT'L | PART NO.(INTENDED USE) | | | | |
| | | | N/A | 3VD5120* - 3D6A - 7H | | | | |
| | .XX± 0.25[0.010] | .XX'± | FINISH | APPD: | | Davy Bu 1/19'18 | DWG NO.: | 301-0000-3122 |
| N/A | | | CHKD: | Z.J.Chen 1/19'18 | SCALE | SHEET | REV. | |
| .XXX± | .XXX'± | Q'TY | DRAW: | | Noah Ji 1/19'18 | N/A | 1/1 | BX2 |

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